

EAG-2040 & EAG-3040

ENGIS AUTOMATED GRINDERS - SINGLE HEAD, FULL AUTO

The Vertical Wafer Grinding Machine is designed to grind advanced materials to a high degree of precision flatness and surface quality, often reducing or eliminating the need for lapping. The compact design with advanced controls and process monitoring makes this an ideal for use in research & development or for low volume production of advanced components.



FEATURES

1. Strong Structure using Casting Frame
2. High Precision, High Rigidity Linear System
3. PC Based machine for Customer's ease of use
4. Automatic Thickness measuring System
5. Automatic Dressing System (Option)
6. Automatic Cassette to Cassette system
7. Cleaning & Dry system
8. Automatically Save and View Process history and All Data
9. Data Sorting (Save All Data in Excel File)
10. Bar code Reader & Addition function (Option)
11. MES or SECS/GEM system (Option)

	EAG-2040 (8")	EAG-3040 (12")
Dual Wheel Spindle	6kW / 6000rpm	9.5kW / 4000rpm
Single Work Spindle	0.75kW / 400rpm	1.5kW / 260rpm
Work Table Size	Diameter 200mm	Diameter 300mm
Wheel Size	203mm	303mm
Feed Rate	0.0001mm-30,000mm/sec	0.0001mm-30,000mm/sec
Resolution	0.0001mm	0.0001mm
Grinding TTV (SiC Wafer)	0.002mm	0.003mm
Between Wafers (SiC Wafer)	+/-0.002mm	+/-0.002mm
Automatic Measuring System	2 Probe/0.1um/5mm	2 Probe/0.1mm/5mm
Automatic Dressing System	N/A	N/A
MES or SECS/GEM	User Spec. (Optional Item)	User Spec. (Optional Item)
Full Auto Handler	User Spec.	User Spec.
Machine Size	2700 x 1800 x 2280	2700 x 1800 x 2350
Machine Weight	5900 Kg	6100 Kg



Lapping & Polishing



Superabrasive Tools



Bore Honing Systems



Engis® offers state-of-the-art technology in the design of flat lapping systems that meet the most demanding requirements.

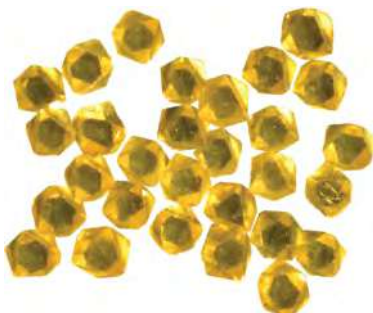


We offer a complete range of superabrasive electroplated products for precision applications.



Multi-Stroke Honing, Single-Pass Bore Finishing & Single-Pass Dual Bore Finishing Systems, Complete Machine Design, Tools & Process Development

Superabrasive Powders



We manufacture high-quality micron diamond & CBN with properties that ensure consistent performance in each application

Mold & Die Polishing



Engis® long trusted brands include Five-Star® diamond compound.

Engis Global Presence



US Engis Corporation



Engis Japan Co., Ltd.



Engis Lapping & Grinding Technology Co., Ltd.



Engis Asia Pacific Pte. Ltd.



Engis of Canada, Ltd.



Engis (Hong Kong) Ltd.



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Engis

ENGIS® CORPORATION

Leader in Superabrasive Finishing Systems

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